

ABSTRACT OF THE DISCLOSURE

A circuit board comprises a base film that is a base layer,
a first conductive circuit manufactured by hardening conductive
paste material formed in a predetermined shape on the base film,
5 a first insulating layer manufactured by hardening insulating
paste material formed on the base film and the first conductive
circuit, and a second conductive circuit manufactured by
hardening conductive paste material in a predetermined shape
on the first insulating layer, wherein an electronic part built-in
10 by the first insulating layer and second insulating layer is
connected to the second conductive circuit, and the first
conductive circuit is connected to the second conductive circuit
through a via hole.